

# IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants:

J.-S. Mok et al.

Attorney Docket No.: LEPA122042

Application No.: 10/717,977

Art Unit: 2822 / Confirmation No.: 8002

Filed:

November 20, 2003

Examiner: M.M. Trinh

Title:

PARALLEL MULTI-LAYER PRINTED CIRCUIT BOARD HAVING

IMPROVED INTERCONNECTION AND METHOD FOR

MANUFACTURING THE SAME

TRANSMITTAL LETTER FOR RESPONSE AFTER FINAL REJECTION UNDER 37 C.F.R. § 1.116

> Seattle, Washington 98101 February 27, 2006

### TO THE COMMISSIONER FOR PATENTS:

#### Response Transmittal Α.

Transmitted herewith is a response to an Office Action in the above-identified application. No additional claim fee is required.

#### Additional Fee Charges or Credit for Overpayment B.

The Commissioner is hereby authorized to charge any fees under 37 C.F.R. §§ 1.16, 1.17 and 1.18 which may be required during the entire pendency of the application, or credit any overpayment, to Deposit Account No. 03-1740. This authorization also hereby includes a request for any extensions of time of the appropriate length required upon the filing of any reply during the entire prosecution of this application.

Respectfully submitted,

CHRISTENSEN O'CONNOR JOHNSON KINDNESSPLLC

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I hereby certify that this correspondence is being deposited with the U.S. Postal Service in a sealed envelope as first class mail with postage thereon fully prepaid and addressed to Mail Stop AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on the below date.

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# MAIL STOP AF RESPONSE UNDER 37 C.F.R. § 1.116 **EXPEDITED PROCEDURE EXAMINING GROUP 2800**

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## RESPONSE AFTER FINAL OFFICE ACTION

Seattle, Washington 98101

February 27, 2006

#### TO THE COMMISSIONER FOR PATENTS:

# **REMARKS**

This paper is filed in response to the Office Action mailed on December 29, 2005. Presently, Claims 1-10 and 14-17 are pending in the application. Claims 2 and 6 are found to contain allowable subject matter. Claims 1, 3-5, 7-10, and 14-17 are rejected. Reconsideration of Claims 1, 3-5, 7-10, and 14-17 is respectfully requested.

### The Rejection of Claims 1, 4, 5, 7, 9, and 15 Under 35 U.S.C. § 102(b)

Claims 1, 4, 5, 7, 9, and 15 are rejected under 35 U.S.C. § 102(b) as being anticipated by applicants' admitted prior art (present specification, page 1, line 20, through page 10; FIGURES 1-4). Applicants respectfully traverse the rejection.

For anticipation, it is necessary that the prior art exactly show every limitation of a claimed invention either expressly or under the principles of inherency.

Claim 1 recites in step (E), "forming circuit patterns on the outermost layers of a board obtained by pressing the circuit layers and the insulating layers."